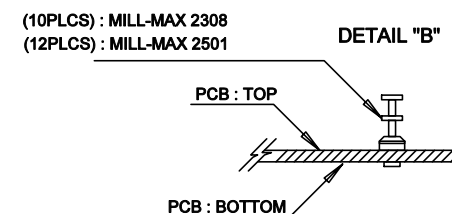
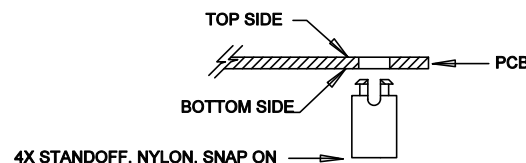
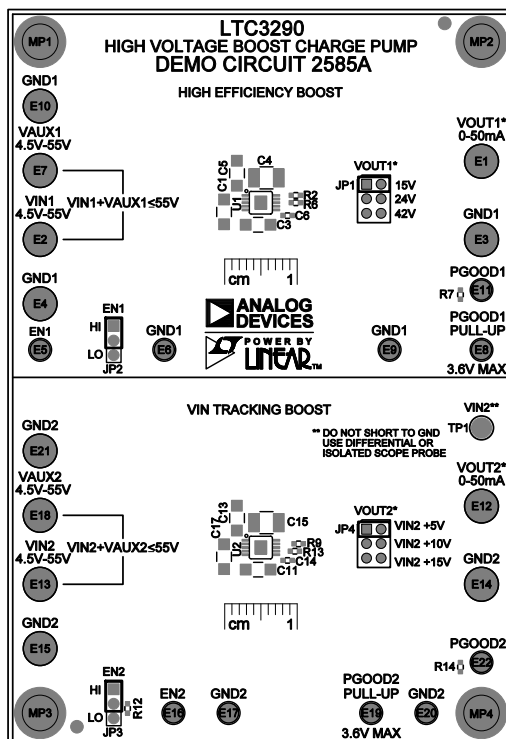


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	03	PRODUCTION	MM	7-22-18

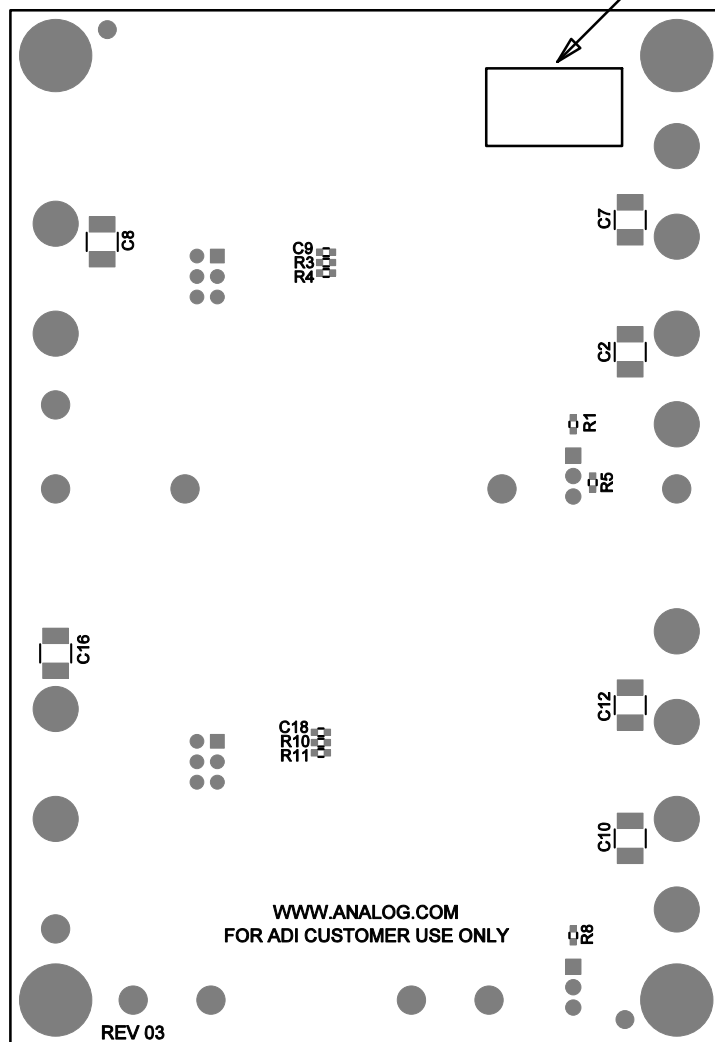
## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS  
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.  
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.



APPROVALS		ANALOG DEVICES   POWER BY LINEAR™ FOR ADI CUSTOMER USE ONLY		
PCB DES	NC	TITLE: TOP ASSEMBLY DRAWING HIGH VOLTAGE BOOST CHARGE PUMP		
APP ENG	MM			
		SIZE	IC NO.	REV.
		N/A	LTC3290 DEMO CIRCUIT 2585A	03
SCALE = NONE		SHT 1 OF 1		

8 DEMO S/N LABEL  
APPLY IN THIS AREA



APPROVALS		ANALOG DEVICES   POWER BY LINEAR™ FOR ADI CUSTOMER USE ONLY	
PCB DES.	NC	TITLE: BOTTOM ASSEMBLY DRAWING  HIGH VOLTAGE BOOST CHARGE PUMP	
APP ENG.	MM		
		SIZE	REV
		N/A	03
SCALE = NONE		SHT 2 of 2	